

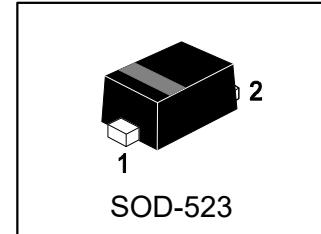
BAT54XV2

S-BAT54XV2

Schottky Barrier Diode

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Extremely Fast Switching Speed
- Low Forward Voltage — 0.35 V (Typ) @ IF = 10 Ma



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
BAT54XV2	JV	3000/Tape&Reel



3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Reverse Voltage	VR	30	V

4. THERMAL CHARACTERISTICS

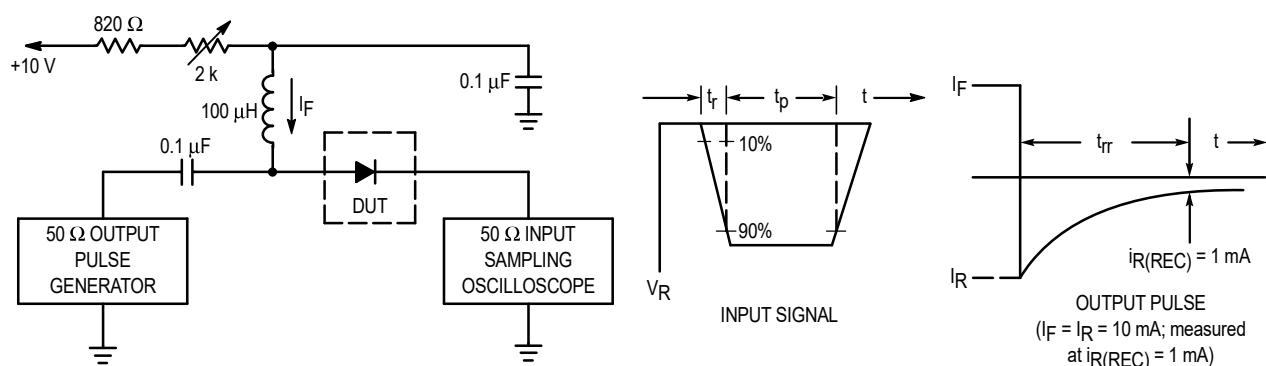
Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-5 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA}	635	°C/W
Junction and Storage temperature	T _{J,Tstg}	-40 ~ +125	°C

1. FR-5 = 1.0×0.75×0.062 in.



5. ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ C$)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage ($I_R = 10 \mu A$)	VBR	30	-	-	V
Total Capacitance ($V_R = 1.0 V$, $f = 1.0 \text{ MHz}$)	C _T	-	-	10	pF
Reverse Leakage ($V_R = 25 V$)	I _R	-	0.5	2	μA
Forward voltage ($I_F = 0.1 \text{ mA}$) ($I_F = 1 \text{ mA}$) ($I_F = 10 \text{ mA}$) ($I_F = 30 \text{ mA}$) ($I_F = 100 \text{ mA}$)	V _F	- - - - -	0.22 0.29 0.35 0.41 0.52	0.24 0.32 0.4 0.5 1	V
Reverse Recovery Time ($I_F = I_R = 10 \text{ mA}$, $I_{R(\text{REC})} = 1.0 \text{ mA}$)	t _{rr}	-	-	5	nS
Forward Current (DC)	I _F	-	-	200	mA
Repetitive Peak Forward Current	I _{FRM}	-	-	300	mA
Non-Repetitive Peak Forward Current ($t < 1.0 \text{ s}$)	I _{FSM}	-	-	600	mA

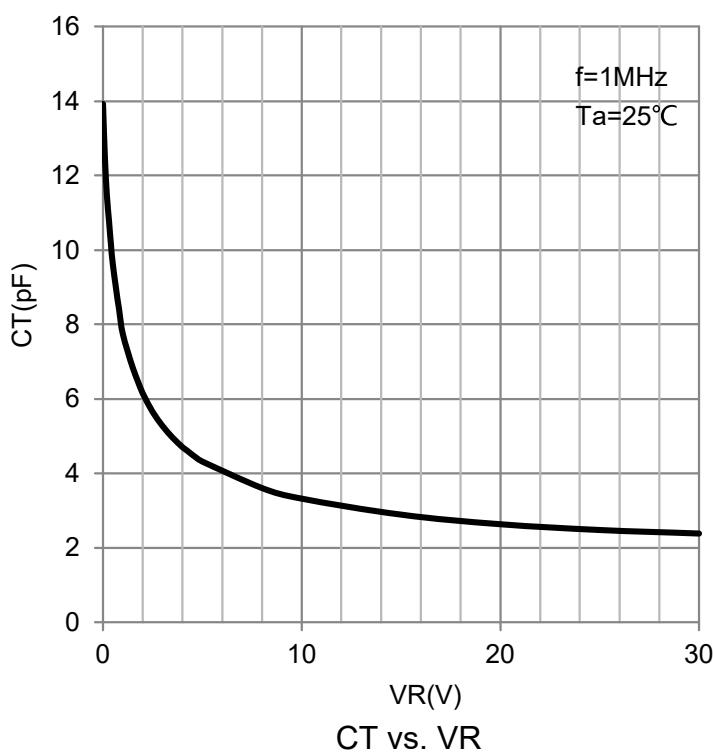
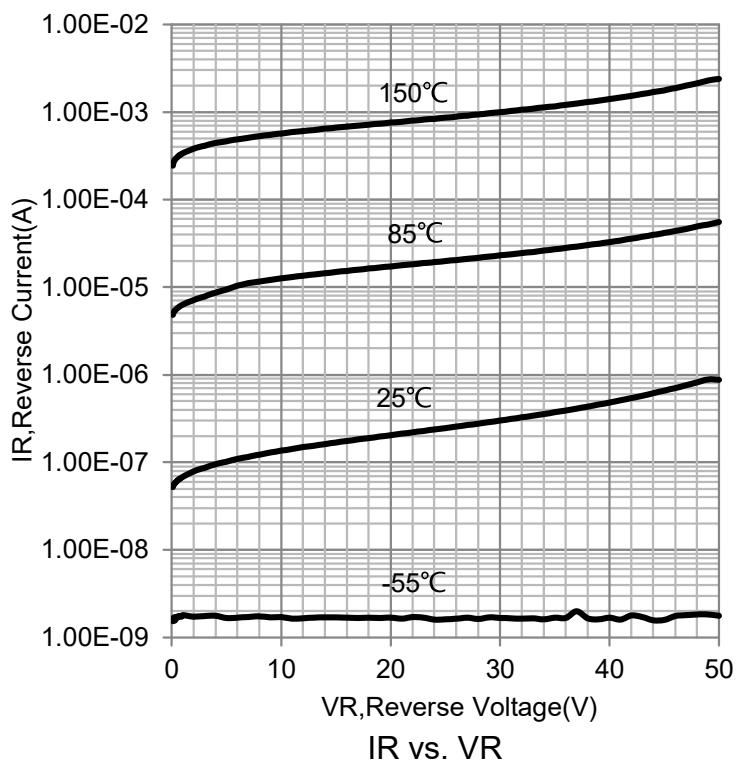
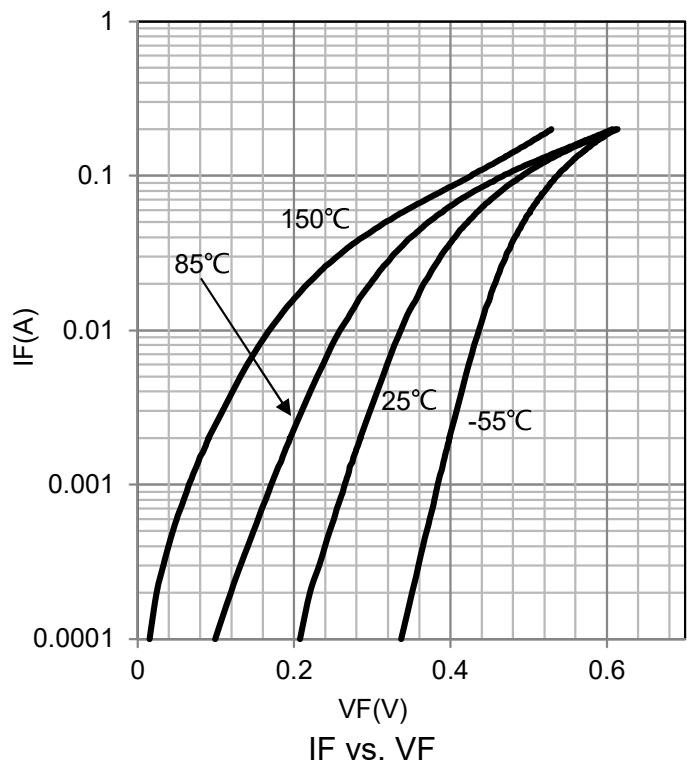


Notes: 1. A 2.0 kΩ variable resistor adjusted for a Forward Current (I_F) of 10 mA.
 2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.
 3. $t_p \gg t_{rr}$

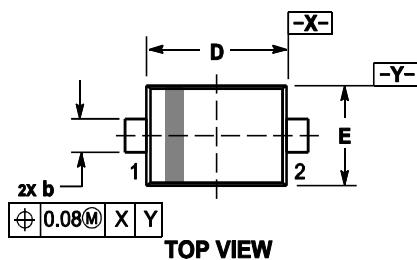
RECOVERY TIME EQUIVALENT TEST CIRCUIT



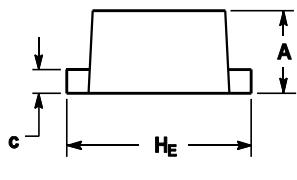
6.ELECTRICAL CHARACTERISTICS CURVES



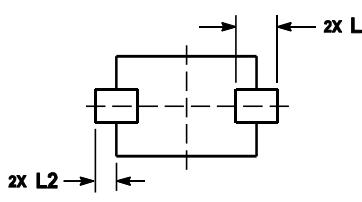
7. OUTLINE AND DIMENSIONS



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
H_E	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L_2	0.15	0.20	0.25	0.006	0.008	0.010

8. SOLDERING FOOTPRINT

